

Amendments to the Claims:

The following listing of claims replaces all other versions of claims previously presented.

Listing of Claims:

Claim 1 (cancelled)

Claim 2 (currently amended): A semiconductor device, comprising:

a semiconductor substrate;

a first insulating film formed on said semiconductor substrate;

a polysilicon resistor film formed on said first insulating film;

a second insulating film formed on said resistor film;

a high heat conductor film consisting of a highly heat-conducting material formed on said second insulating film, said high heat conductor film formed in a predetermined area including an area above said resistor film; and

a pair of terminal wirings formed on said second insulating film and connected to said resistor film,

wherein a thickness of said high heat conductor film is thicker than a thickness of said resistor film.

Claim 3 (original): The semiconductor device according to claim 2, wherein the thickness of said high heat conductor film is twice the thickness of said resistor film or thicker.

Claim 4 (original): The semiconductor device according to claim 2, wherein a width of said high heat conductor film is wider than a width of said resistor film.

Claim 5 (original): The semiconductor device according to claim 2, wherein said high heat conductor film is united with one of said terminal wirings.

Claim 6 (currently amended): A semiconductor device, comprising:

a semiconductor substrate;

a first insulating film formed on said semiconductor substrate;

a polysilicon resistor film formed on said first insulating film;

a second insulating film formed on said resistor film;

a high heat conductor film consisting of a highly heat-conducting material formed on said second insulating film, said high heat conductor film formed in a predetermined area including an area above said resistor film; and

a pair of terminal wirings formed on said second insulating film and connected to said resistor film,

wherein a thickness of said second insulating film is thinner than a thickness of said resistor film, and a thickness of said high heat conductor film is thicker than a thickness of said resistor film.